NOTES:
1) built on PCB PMP2763 RevA
2) inverting BuckBoost, refer to board connection
3) R8 for test purposes only
4) TP1/TP13/TP16 to connect Network Analyzer
5) designed for pulsed load 10mA / 140mA
6) for max. effcy L2 could be DR125-221-R
   (size 12.5mm x 12.5mm x 6mm)

ASSEMBLY:
1) R7 SHORT
2) C8, C11 open
3) R4, R6, R9 open
4) L1, D1 open
5) TP5, TP7, TP8, TP11, TP15 open
6) C2, C3, C5 will not meet pattern
7) D2 - SMA on SMB pattern
8) pattern L2 matches up to DR127 series

Revision History

Revision | Notes
---|---
A | * First release: RHPZ 17kHz, Fco 1kHz
A1 | * Fco 2.4kHz
B | * Fco 5.0kHz
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